

MOSFET – Power, Single N-Channel

40 V, 7.3 mΩ, 52 A

NVMFS5C466NL

Features

- Small Footprint (5x6 mm) for Compact Design
- Low $R_{DS(on)}$ to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- NVMFS5C466NLWF – Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-to-Source Voltage		V_{DSS}	40	V
Gate-to-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current $R_{\theta JC}$ (Notes 1, 3)	Steady State	I_D	52	A
			37	
Power Dissipation $R_{\theta JC}$ (Note 1)		P_D	37	W
			19	
Continuous Drain Current $R_{\theta JA}$ (Notes 1, 2, 3)	Steady State	I_D	16	A
			11	
Power Dissipation $R_{\theta JA}$ (Notes 1 & 2)		P_D	3.5	W
			1.75	
Pulsed Drain Current	$T_A = 25^\circ\text{C}$, $t_p = 10 \mu\text{s}$	I_{DM}	238.6	A
Operating Junction and Storage Temperature		T_J , T_{stg}	-55 to +175	°C
Source Current (Body Diode)		I_S	31.25	A
Single Pulse Drain-to-Source Avalanche Energy ($I_{L(pk)} = 2.93 \text{ A}$)		E_{AS}	65	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		T_L	260	°C

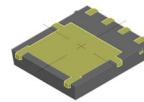
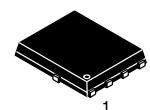
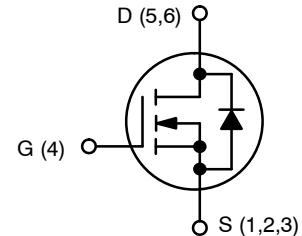
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case – Steady State	$R_{\theta JC}$	4.0	°C/W
Junction-to-Ambient – Steady State (Note 2)	$R_{\theta JA}$	43	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.

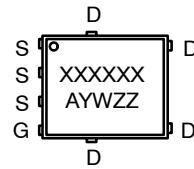
$V_{(BR)DSS}$	$R_{DS(on)} \text{ MAX}$	$I_D \text{ MAX}$
40 V	7.3 mΩ @ 10 V	52 A
	12 mΩ @ 4.5 V	



DFN5 5x6, 1.27P
(SO-8FL)
CASE 488AA

DFNW5 5x6
(FULL-CUT SO8FL WF)
CASE 507BA

MARKING DIAGRAM



XXXXXX = 5C466NL
(NVMFS5C466NL) or
466LWF
(NVMFS5C466NLWF)

A = Assembly Location

Y = Year

W = Work Week

ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 5 of this data sheet.

NVMFS5C466NL

3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Typ	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$		40	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(\text{BR})\text{DSS}}/T_J$			-	25	-	$\text{mV}/^\circ\text{C}$
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{GS}} = 0 \text{ V}$, $V_{\text{DS}} = 40 \text{ V}$	$T_J = 25^\circ\text{C}$	-	-	10	μA
			$T_J = 125^\circ\text{C}$	-	-	250	
Gate-to-Source Leakage Current	I_{GSS}	$V_{\text{DS}} = 0 \text{ V}$, $V_{\text{GS}} = 20 \text{ V}$		-	-	100	nA

ON CHARACTERISTICS (Note 4)

Gate Threshold Voltage	$V_{\text{GS}(\text{TH})}$	$V_{\text{GS}} = V_{\text{DS}}$, $I_D = 30 \mu\text{A}$		1.2	-	2.2	V
Threshold Temperature Coefficient	$V_{\text{GS}(\text{TH})}/T_J$			-	-4.9	-	$\text{mV}/^\circ\text{C}$
Drain-to-Source On Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 4.5 \text{ V}$	$I_D = 10 \text{ A}$	-	9.7	12	$\text{m}\Omega$
Drain-to-Source On Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10 \text{ V}$	$I_D = 10 \text{ A}$	-	6.1	7.3	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}} = 15 \text{ V}$, $I_D = 10 \text{ A}$		-	33	-	S

CHARGES, CAPACITANCES & GATE RESISTANCE

Input Capacitance	C_{iss}	$V_{\text{GS}} = 0 \text{ V}$, $f = 1 \text{ MHz}$, $V_{\text{DS}} = 25 \text{ V}$	-	860	-	pF
Output Capacitance	C_{oss}		-	360	-	
Reverse Transfer Capacitance	C_{rss}		-	15	-	
Total Gate Charge	$Q_{\text{G}(\text{TOT})}$	$V_{\text{GS}} = 4.5 \text{ V}$, $V_{\text{DS}} = 32 \text{ V}$; $I_D = 10 \text{ A}$	-	7	-	nC
Total Gate Charge	$Q_{\text{G}(\text{TOT})}$		-	16	-	
Threshold Gate Charge	$Q_{\text{G}(\text{TH})}$		-	1.8	-	
Gate-to-Source Charge	Q_{GS}		-	3.3	-	
Gate-to-Drain Charge	Q_{GD}		-	2.5	-	
Plateau Voltage	V_{GP}		-	3.4	-	V

SWITCHING CHARACTERISTICS (Note 5)

Turn-On Delay Time	$t_{\text{d}(\text{ON})}$	$V_{\text{GS}} = 10 \text{ V}$, $V_{\text{DS}} = 32 \text{ V}$, $I_D = 10 \text{ A}$, $R_G = 1 \Omega$	-	8	-	ns
Rise Time	t_r		-	24	-	
Turn-Off Delay Time	$t_{\text{d}(\text{OFF})}$		-	29	-	
Fall Time	t_f		-	6	-	

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	V_{SD}	$V_{\text{GS}} = 0 \text{ V}$, $I_S = 10 \text{ A}$	$T_J = 25^\circ\text{C}$	-	0.84	1.2	V
			$T_J = 125^\circ\text{C}$	-	0.71	-	
Reverse Recovery Time	t_{RR}	$V_{\text{GS}} = 0 \text{ V}$, $dI_S/dt = 100 \text{ A}/\mu\text{s}$, $I_S = 10 \text{ A}$	-	24	-	ns	
Charge Time	t_a		-	11	-		
Discharge Time	t_b		-	12	-		
Reverse Recovery Charge	Q_{RR}		-	11	v	nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

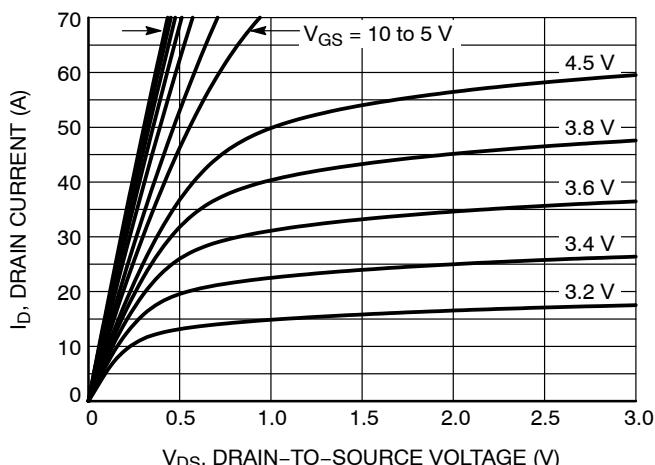


Figure 1. On-Region Characteristics

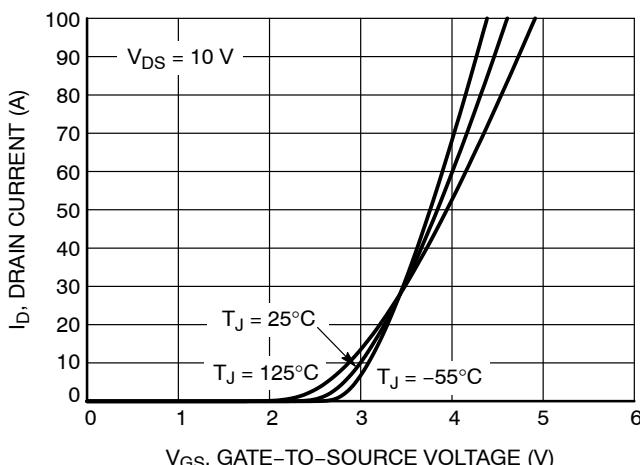


Figure 2. Transfer Characteristics

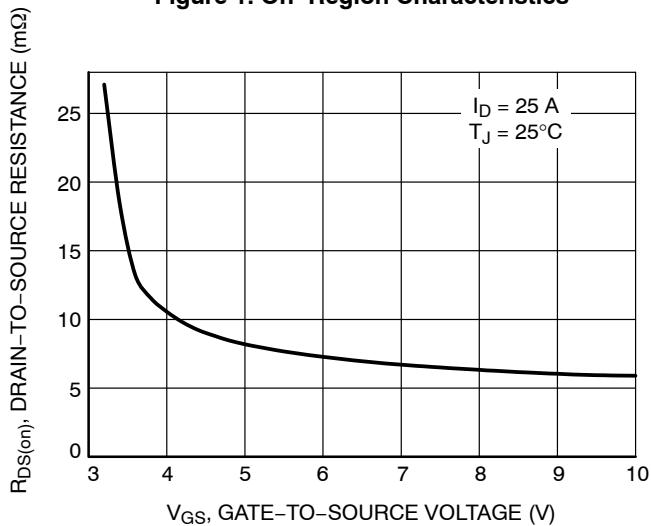


Figure 3. On-Resistance vs. Gate-to-Source Voltage

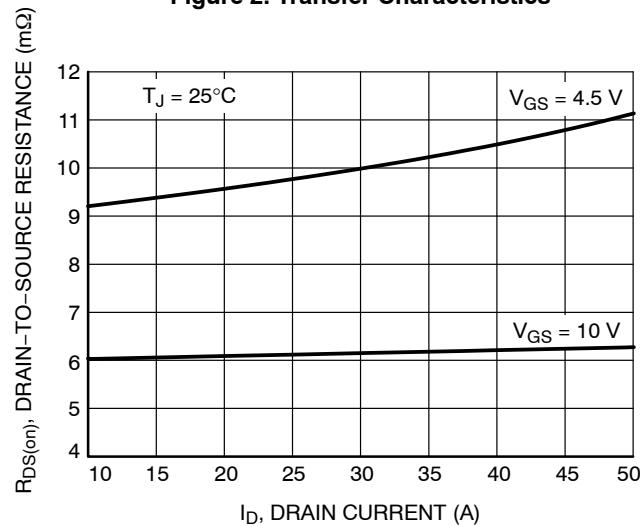


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

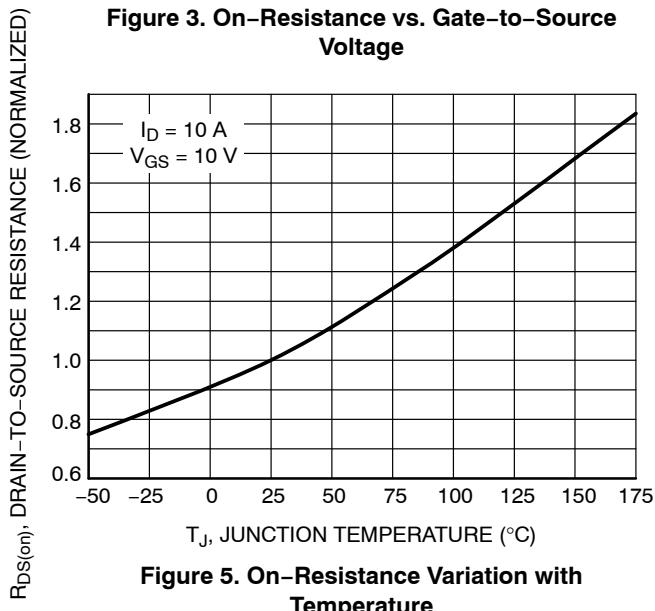


Figure 5. On-Resistance Variation with Temperature

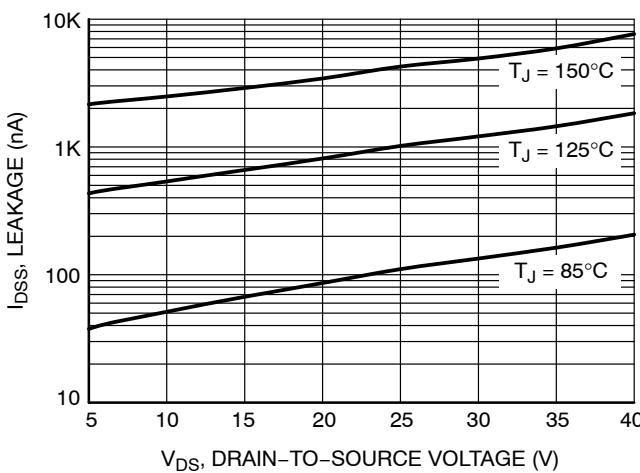
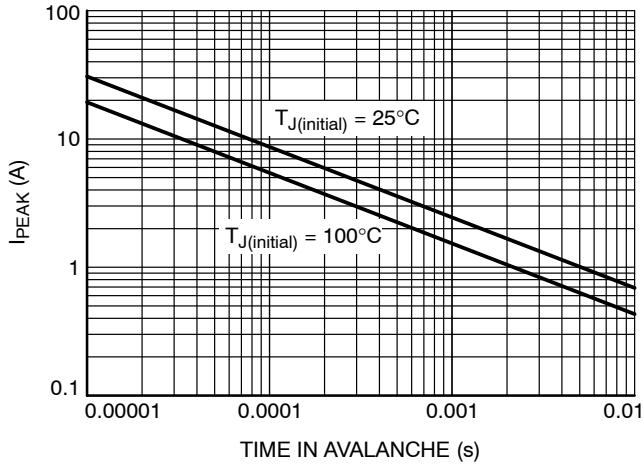
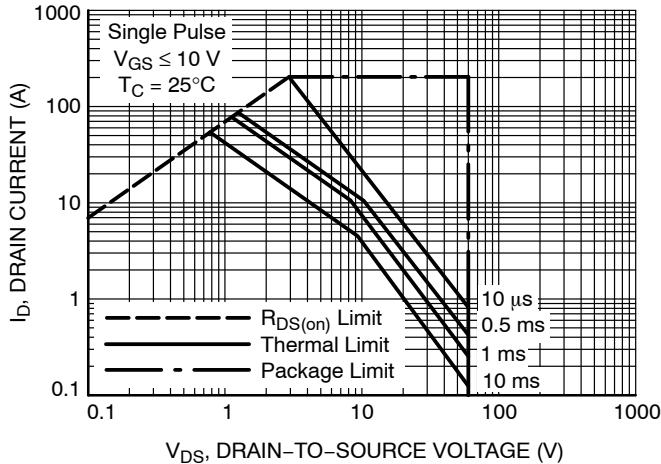
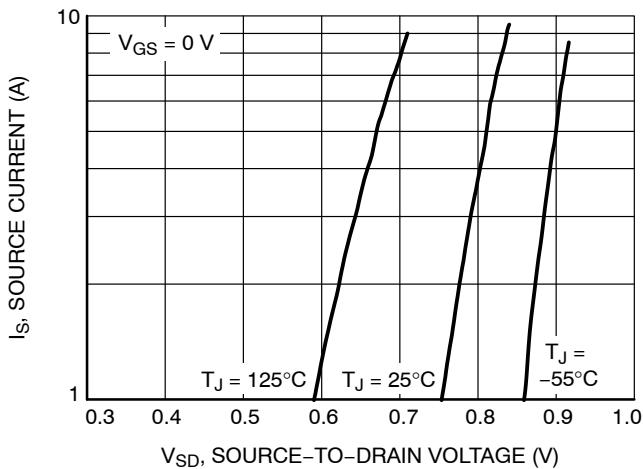
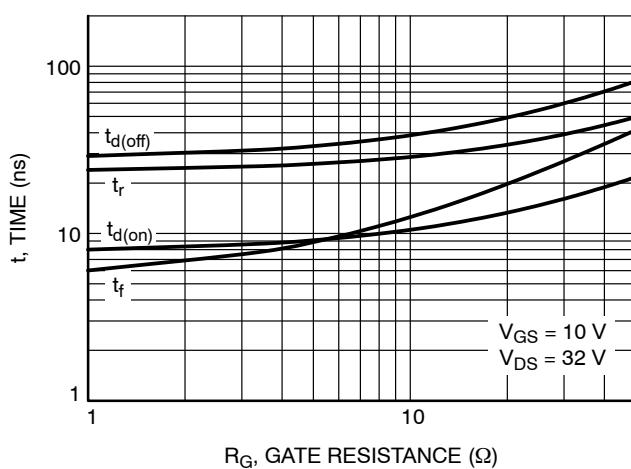
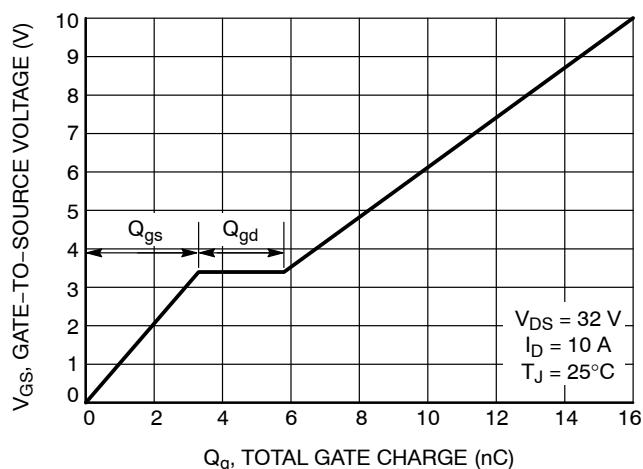
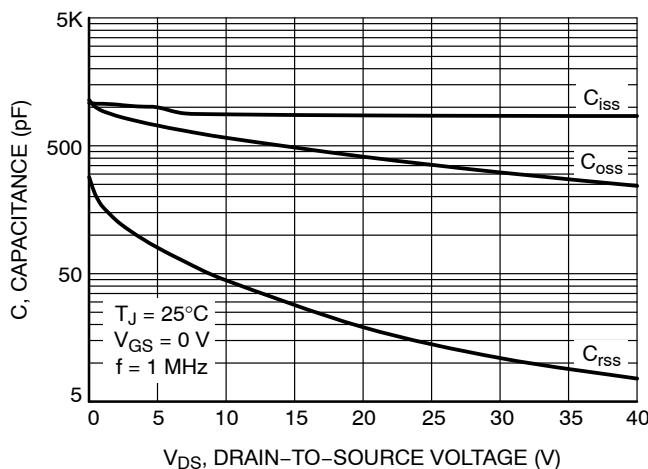
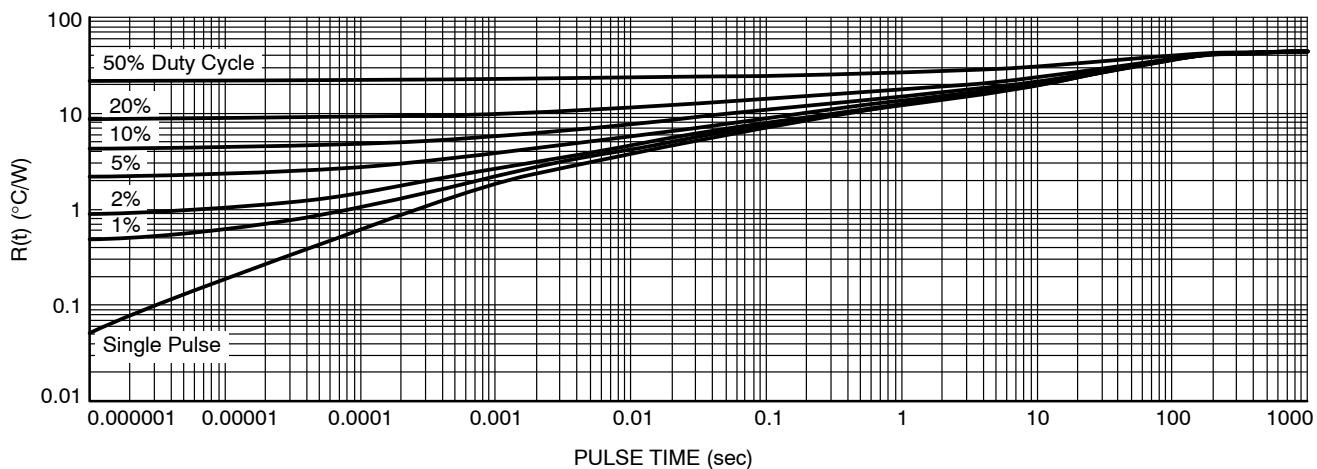


Figure 6. Drain-to-Source Leakage Current vs. Voltage

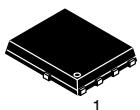
TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS**Figure 13. Thermal Response****DEVICE ORDERING INFORMATION**

Device	Marking	Package	Shipping [†]
NVMFS5C466NLT1G	5C466L	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free)	1500 / Tape & Reel
NVMFS5C466NLWFT1G	466LWF	DFNW5, 5x6 (FULL-CUT SO8FL WF) (Pb-Free, Wettable Flanks)	1500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).



SCALE 2:1

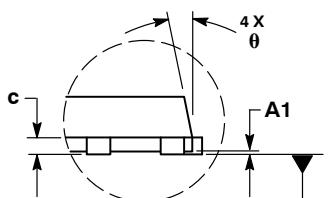
DFN5 5x6, 1.27P
(SO-8FL)
CASE 488AA
ISSUE N

DATE 25 JUN 2018

NOTES:

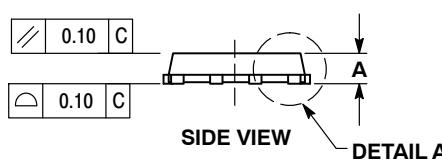
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	---	0.05
b	0.33	0.41	0.51
c	0.23	0.28	0.33
D	5.00	5.15	5.30
D1	4.70	4.90	5.10
D2	3.80	4.00	4.20
E	6.00	6.15	6.30
E1	5.70	5.90	6.10
E2	3.45	3.65	3.85
e	1.27 BSC		
G	0.51	0.575	0.71
K	1.20	1.35	1.50
L	0.51	0.575	0.71
L1	0.125 REF		
M	3.00	3.40	3.80
θ	0 °	---	12 °

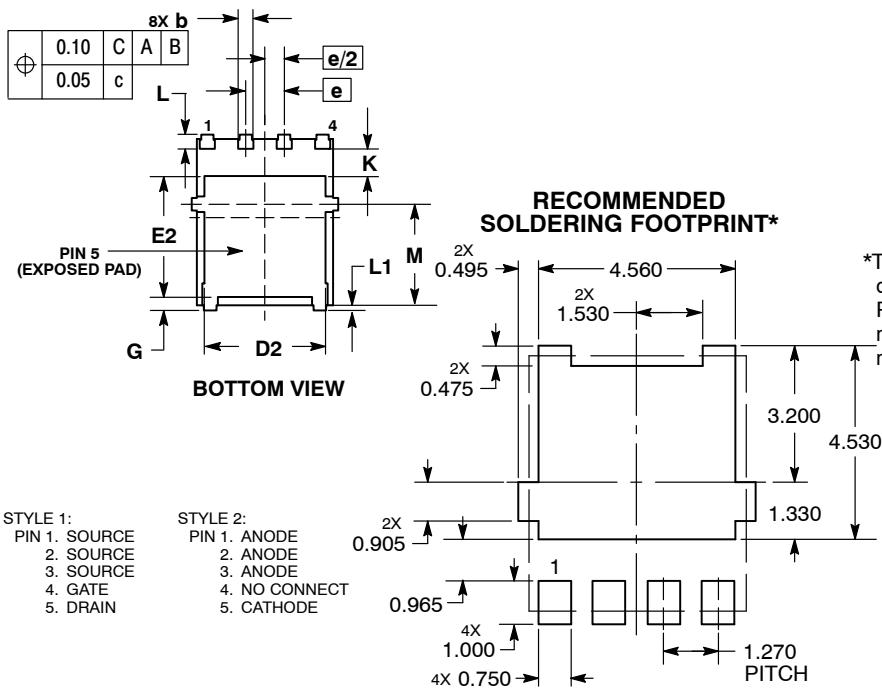


DETAIL A

SEATING PLANE



DETAIL A



STYLE 1:
PIN 1. SOURCE
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN

STYLE 2:
PIN 1. ANODE
2. ANODE
3. ANODE
4. NO CONNECT
5. CATHODE

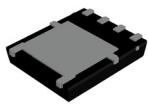
DIMENSIONS: MILLIMETERS

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

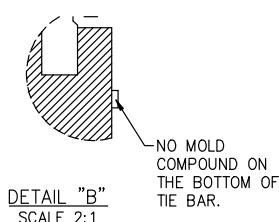
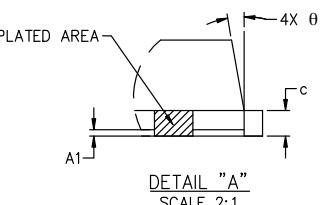
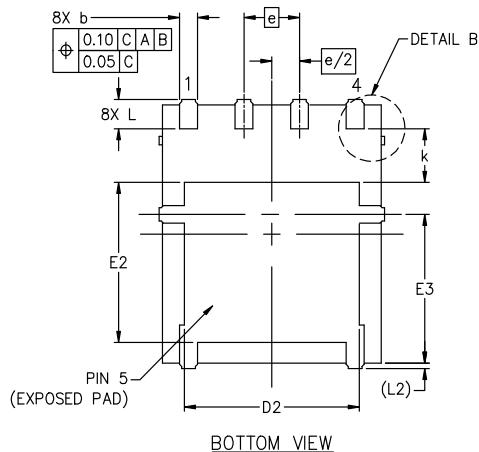
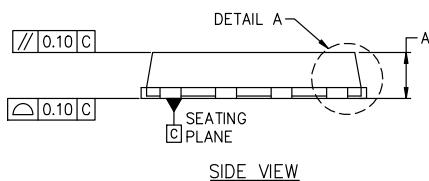
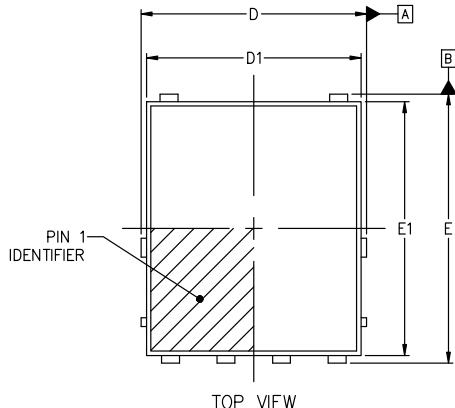
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DESCRIPTION:	DFN5 5x6, 1.27P (SO-8FL)	PAGE 1 OF 1

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DFNW5 4.90x5.90x1.00, 1.27P
CASE 507BA
ISSUE C

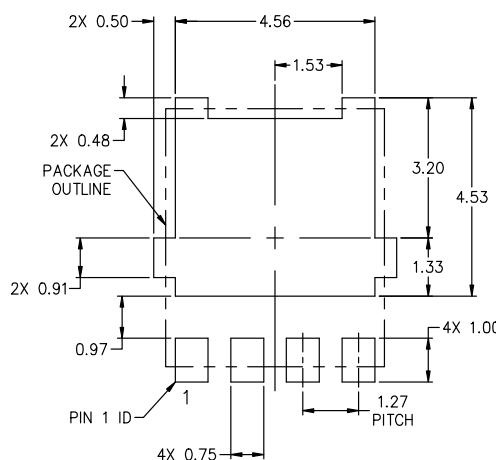
DATE 19 SEP 2024



NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-2018.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
4. THIS PACKAGE CONTAINS WETTABLE FLANK DESIGN FEATURES TO AID IN FILLET FORMATION ON THE LEADS DURING MOUNTING.

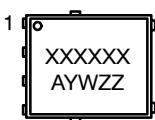
DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	---	0.05
b	0.33	0.41	0.51
c	0.23	0.28	0.33
D	5.00	5.15	5.30
D1	4.70	4.90	5.10
D2	3.80	4.00	4.20
E	6.00	6.15	6.30
E1	5.70	5.90	6.10
E2	3.45	3.65	3.85
E3	3.00	3.40	3.80
e		1.27 BSC	
k	1.20	1.35	1.50
L	0.51	0.57	0.71
L2		0.15 REF.	
θ	0°	6°	12°



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

**GENERIC
MARKING DIAGRAM***



XXXXXX = Specific Device Code
 A = Assembly Location
 Y = Year
 W = Work Week
 ZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking.
 Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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